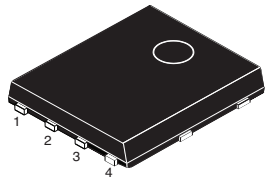
STL92N10F7AG

Automotive-grade N-channel 100 V, 0.008 Ω typ.,16 A STripFET™ F7 Power MOSFET in a PowerFLAT™ 5x6 package

Datasheet - production data



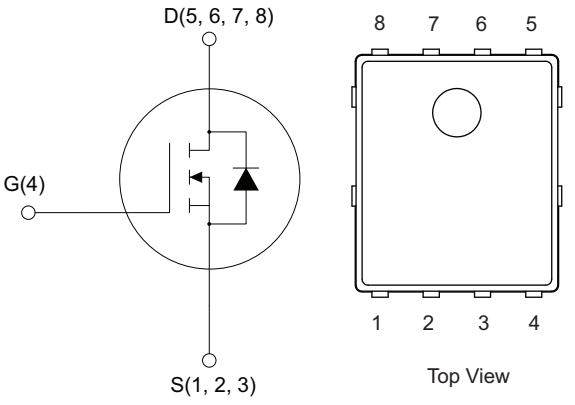
PowerFLAT™5x6

Features

Order code	V_{DS}	$R_{DS(on)}$ max	I_D	P_{TOT}
STL92N10F7AG	100 V	0.0095 Ω	16 A	5 W

- Designed for automotive applications and AEC-Q101 qualified
- Among the lowest $R_{DS(on)}$ on the market
- Excellent figure of merit (FoM)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness
- Wettable flank package

Figure 1. Internal schematic diagram



Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1. Device summary

Order code	Marking	Package	Packaging
STL92N10F7AG	92N10F7	PowerFLAT™ 5x6	Tape and reel

This is information on a product in full production. www.st.com

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	100	V
V_{GS}	Gate-source voltage	± 20	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	70	A
I_D (1)	Drain current (continuous) at T_C = 100 °C	50	A
I_D (2)	Drain current (continuous) at T_{pcb} = 25 °C	16	A
I_D (2)	Drain current (continuous) at T_{pcb} = 100 °C	11	A
I_{DM} (2)(3)	Drain current (pulsed)	64	A
P_{TOT} (1)	Total dissipation at T_C = 25 °C	100	W
P_{TOT} (2)	Total dissipation at T_{pcb} = 25 °C	5	W
T_{stg}	Storage temperature	-55 to 175 °C	°C
T_j	Operating junction temperature		

1. This value is rated according to $R_{thj\text{-}c}$
2. This value is rated according to $R_{thj\text{-}pcb}$
3. Pulse width limited by safe operating area.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb max	31	°C/W
$R_{thj\text{-}case}$	Thermal resistance junction-case max	1.5	°C/W

1. When mounted on FR-4 board of 1 inch^2, 2 oz Cu.

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 250 µA, V_{GS} = 0	100			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 100 V			1	µA
		V_{DS} = 100 V, T_C=125 °C			100	µA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2.5	3.5	4.5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 8 A		0.008	0.0095	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0	-	3100	-	pF
C_{oss}	Output capacitance		-	700	-	pF
C_{rss}	Reverse transfer capacitance		-	45	-	pF
Q_g	Total gate charge	V_{DD} = 50 V, I_D = 16 A, V_{GS} = 10 V (see *Figure 14*)	-	45	-	nC
Q_{gs}	Gate-source charge		-	18	-	nC
Q_{gd}	Gate-drain charge		-	13	-	nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 50 V, I_D = 8 A, R_G = 4.7 Ω, V_{GS} = 10 V (see *Figure 15* and *Figure 18*)	-	19	-	ns
t_r	Rise time		-	32	-	ns
$t_{d(off)}$	Turn-off delay time		-	36	-	ns
t_f	Fall time		-	13	-	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		16	A
I_{SDM} (1)	Source-drain current (pulsed)		-		64	A
V_{SD} (2)	Forward on voltage	I_{SD} = 16 A, V_{GS} = 0	-		1.1	V
t_{rr}	Reverse recovery time	I_{SD} = 16 A, di/dt = 100 A/µs V_{DD} = 80 V, T_j=150 °C (see *Figure 18*)	-	70		ns
Q_{rr}	Reverse recovery charge		-	125		nC
I_{RRM}	Reverse recovery current		-	3.6		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

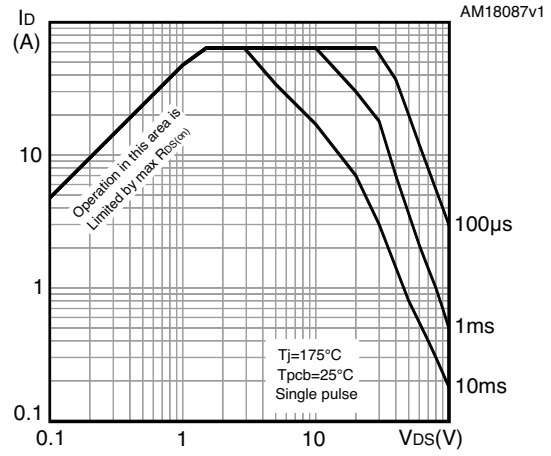


Figure 3. Thermal impedance

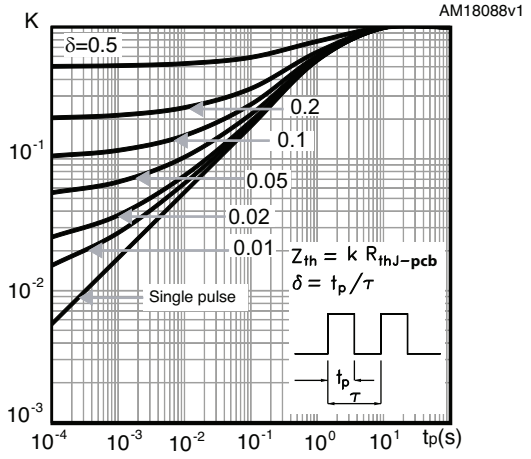


Figure 4. Output characteristics

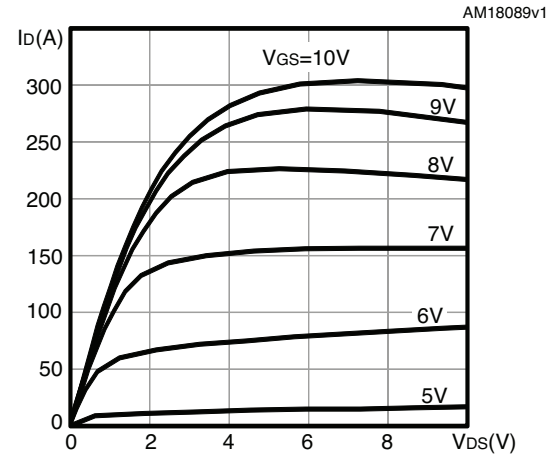


Figure 5. Transfer characteristics

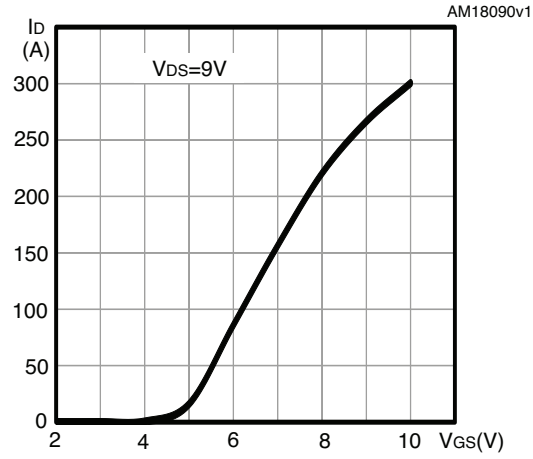


Figure 6. Gate charge vs gate-source voltage

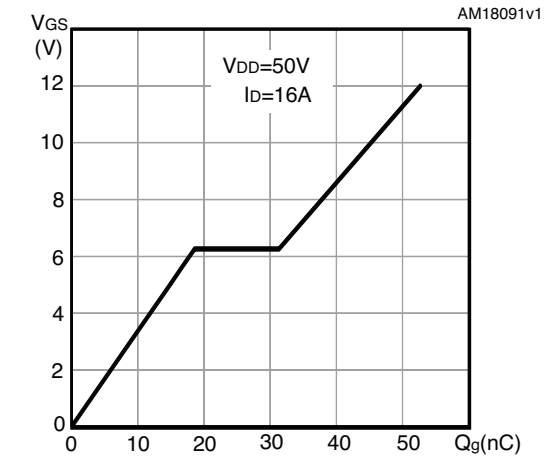


Figure 7. Static drain-source on-resistance

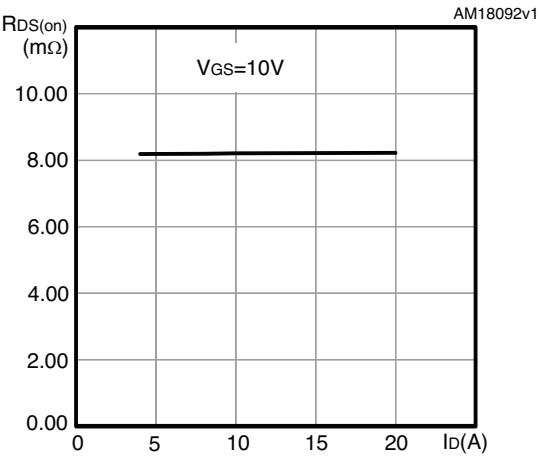


Figure 8. Capacitance variations

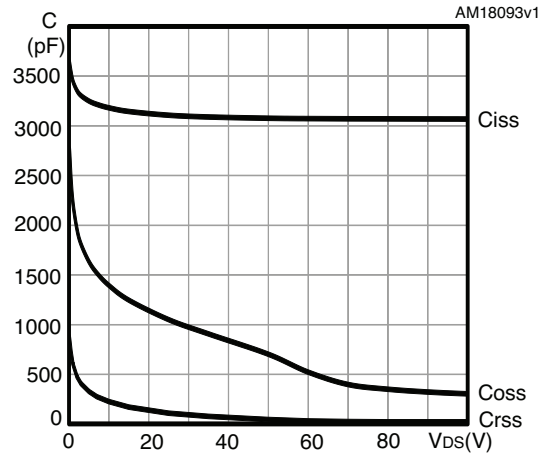


Figure 9. Normalized gate threshold voltage vs temperature

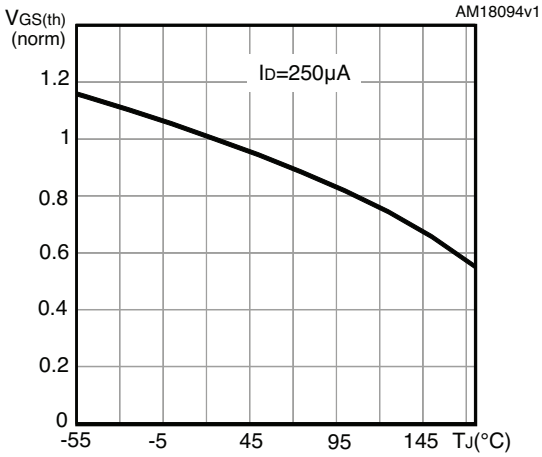


Figure 10. Normalized on-resistance vs temperature

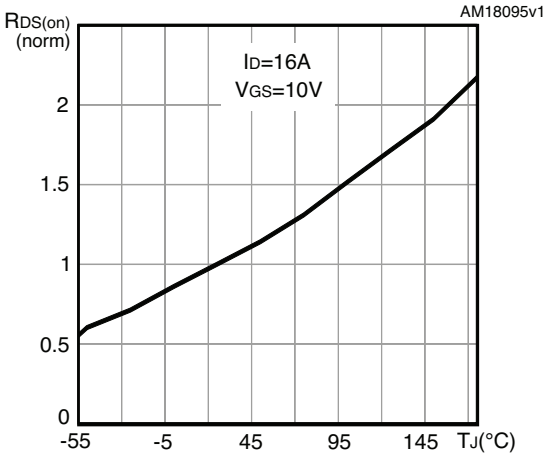


Figure 11. Normalized $V_{(BR)DSS}$ vs temperature

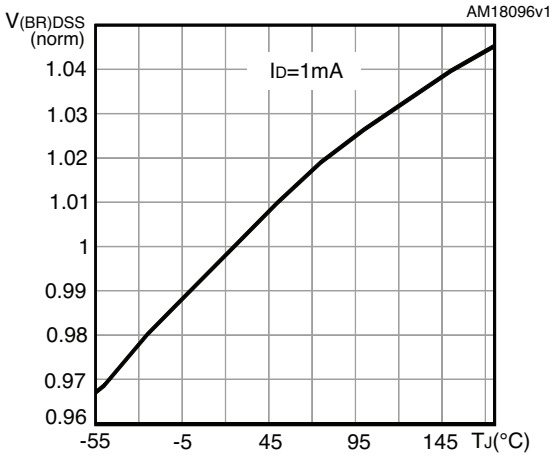
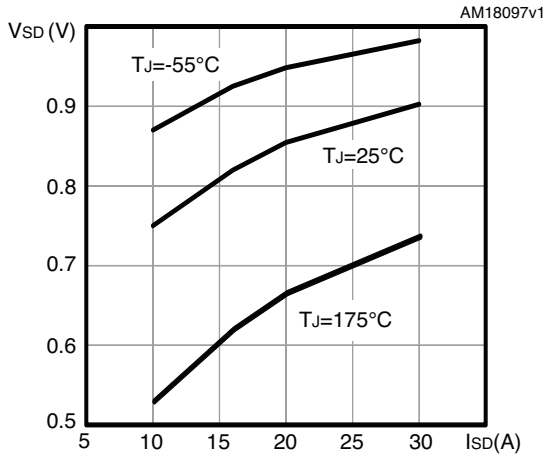


Figure 12. Source-drain diode forward characteristics



3 Test circuits

Figure 13. Switching times test circuit for resistive load

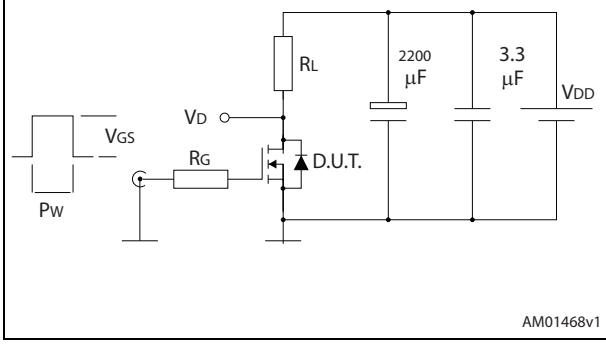


Figure 14. Gate charge test circuit

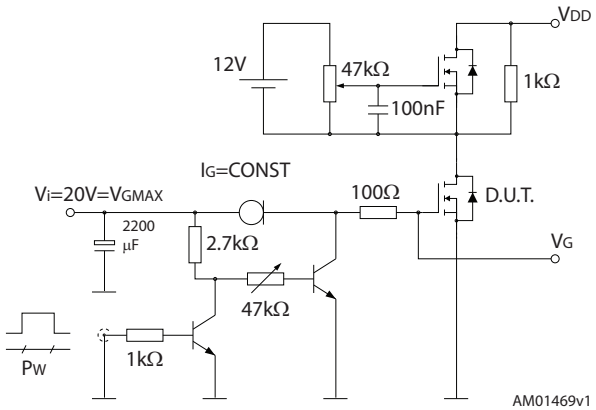


Figure 15. Test circuit for inductive load switching and diode recovery times

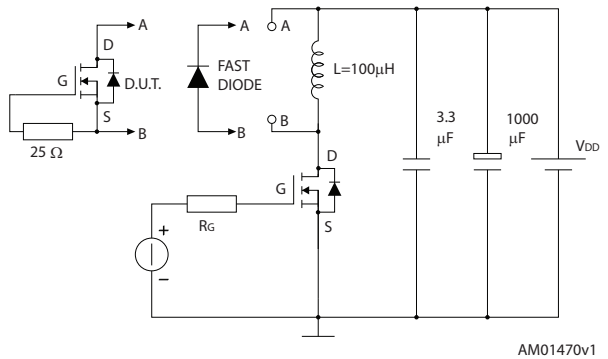


Figure 16. Unclamped inductive load test circuit

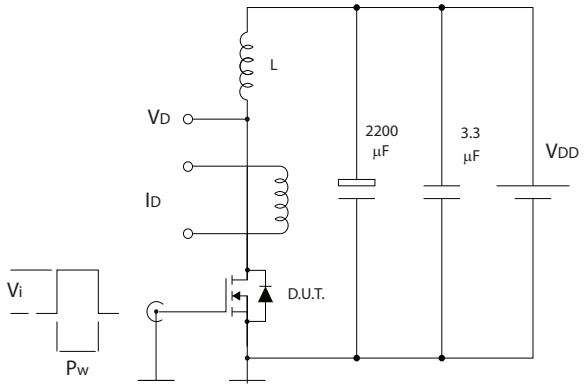


Figure 17. Unclamped inductive waveform

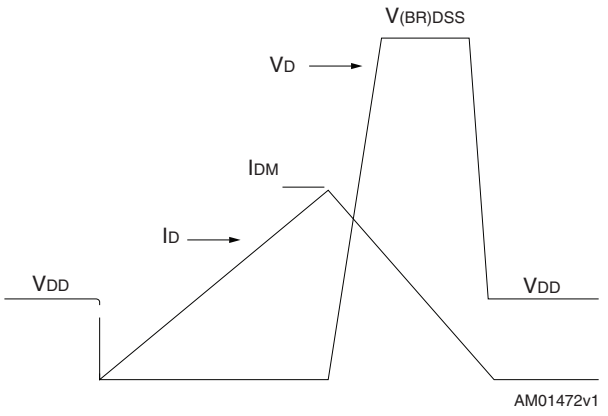
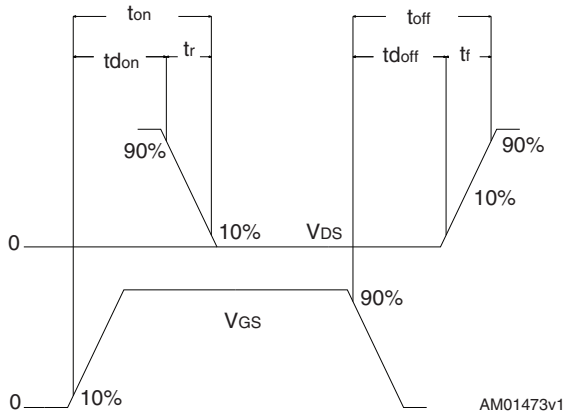


Figure 18. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 WF type R package information

Figure 19. PowerFLAT™ 5x6 WF type R package outline

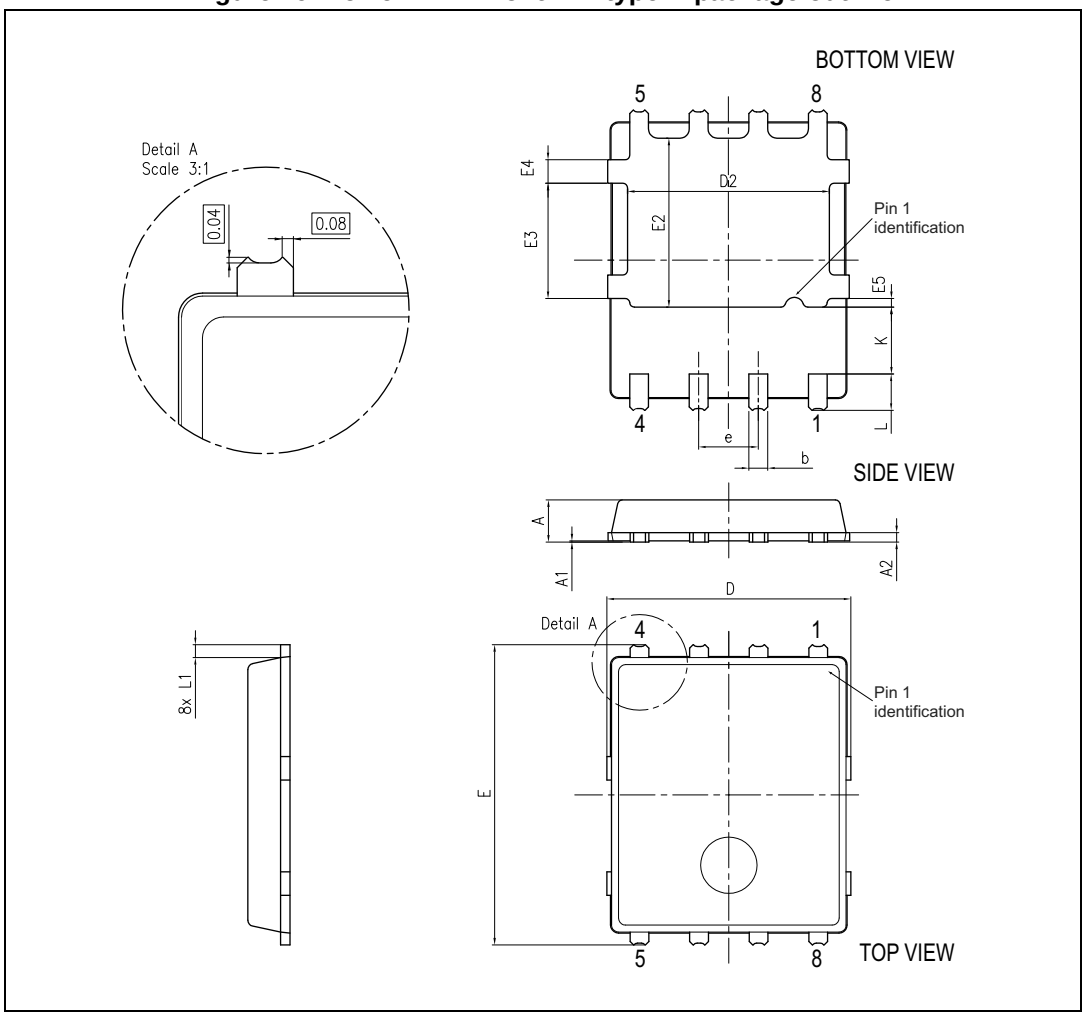
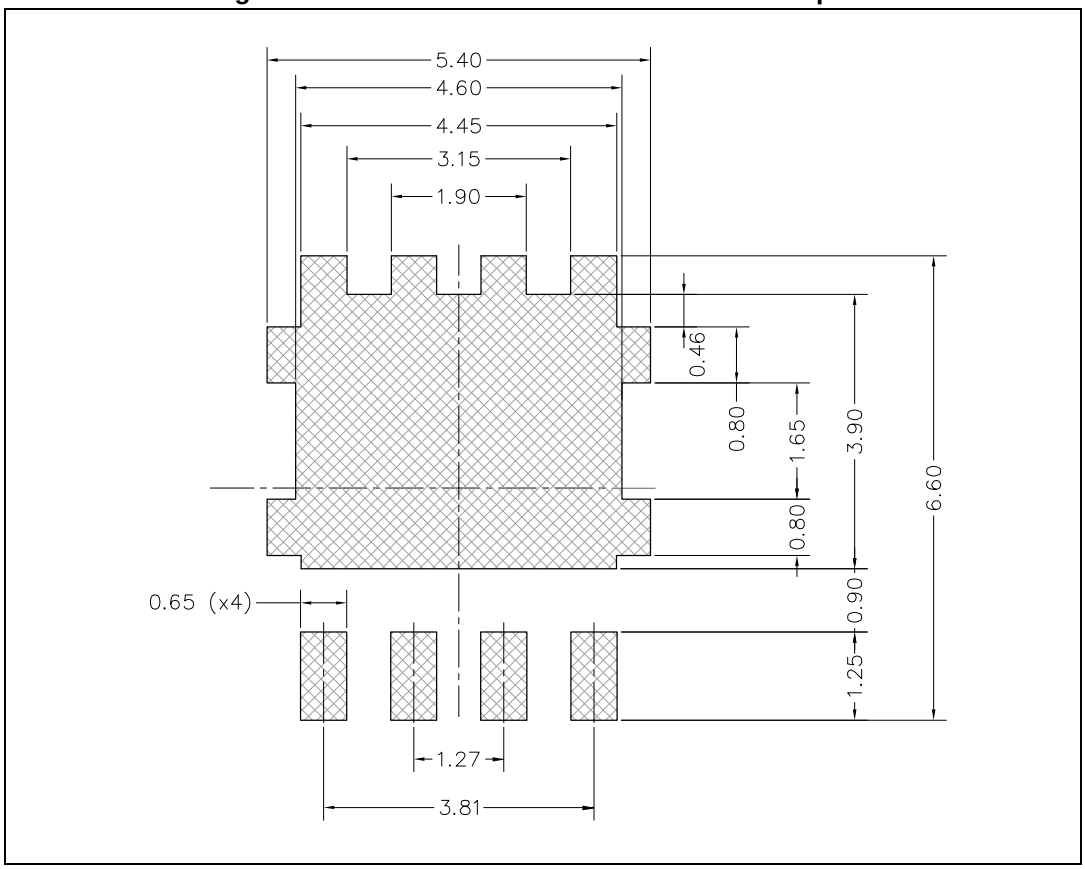


Table 8. PowerFLAT™ 5x6 WF type R mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D	5.00	5.20	5.40
E	6.20	6.40	6.60
D2	4.15		4.45
E2	3.50		3.70
e		1.27	
L	0.70		0.90
L1		0.275	
K	1.275		1.575
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28

Figure 20. PowerFLAT™ 5x6 recommended footprint



4.2 PowerFLAT™ 5x6 packing information

Figure 21. PowerFLAT™ 5x6 type WF tape[(a)]

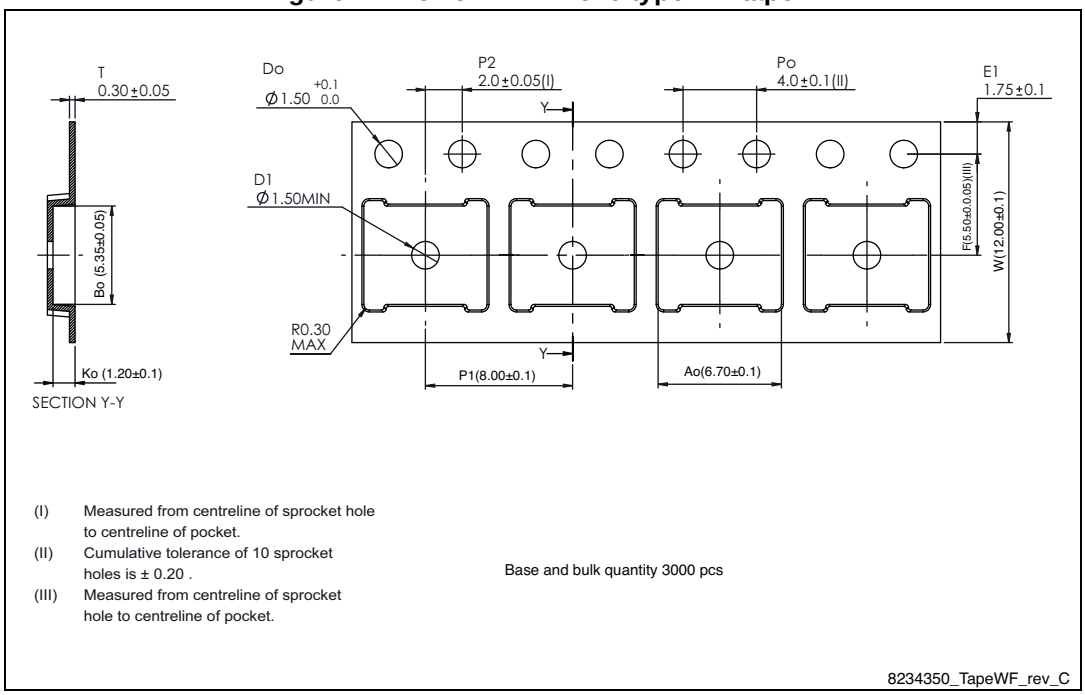
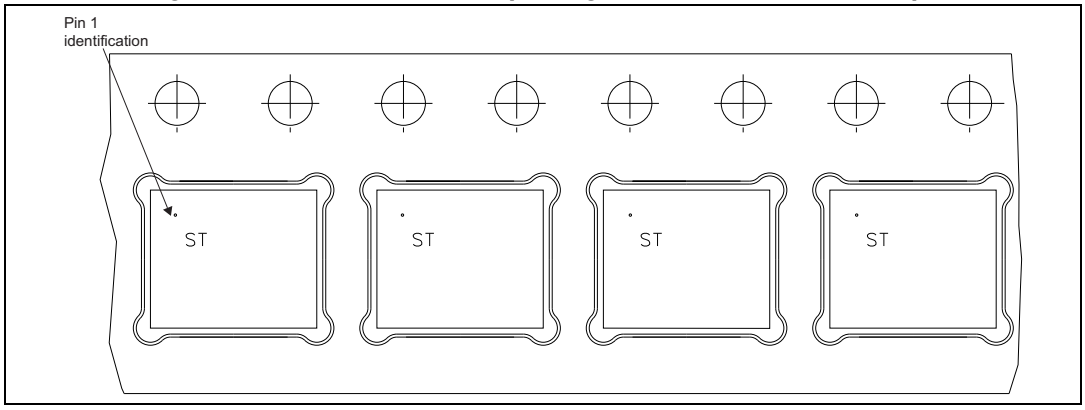
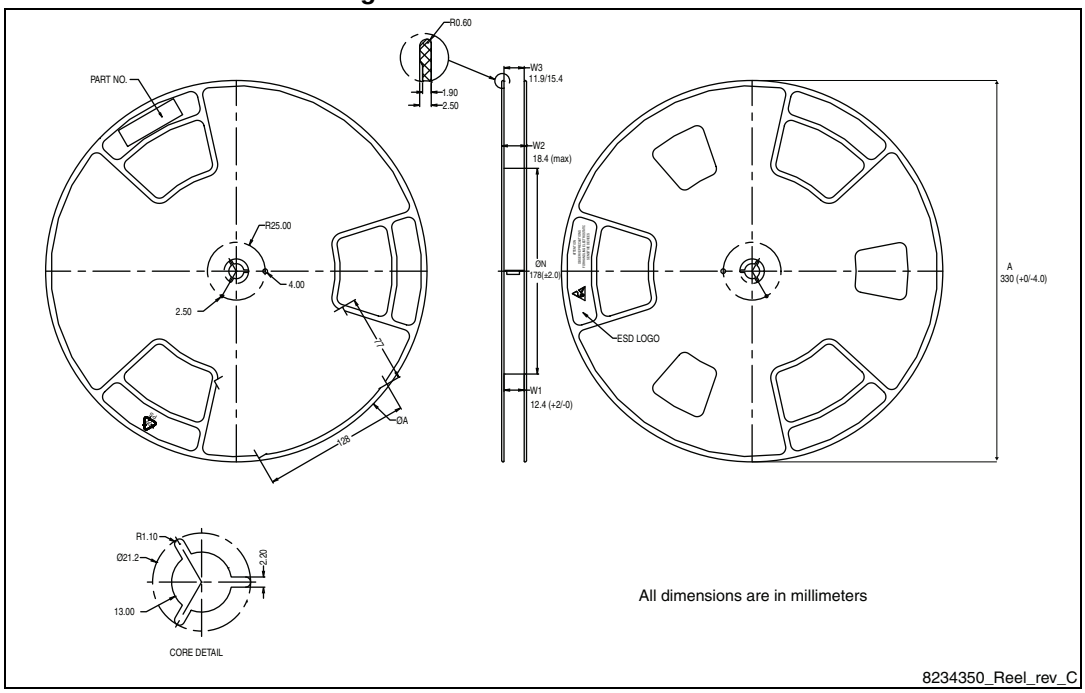


Figure 22. PowerFLAT™ 5x6 package orientation in carrier tape



a. All dimensions are in millimeters.

Figure 23. PowerFLAT™ 5x6 reel



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
16-Oct-2014	1	First release.
12-Oct-2015	2	Updated: *Section 4.1: PowerFLAT™ 5x6 WF type R package information* Datasheet promoted from preliminary data to production data Minor text changes

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